# **IRFD9010**

**Vishay Siliconix** 



**HVMDIP** 

**PRODUCT SUMMARY** 

 $V_{DS}(V)$ 

R<sub>DS(on)</sub> (Ω)

Q<sub>gs</sub> (nC)

Q<sub>ad</sub> (nC)

Q<sub>q</sub> (Max.) (nC)

Configuration

GC

P-Channel MOSFET

0.50

- 50

11

3.8

4.1

Single

 $V_{GS} = -10 V$ 

# **Power MOSFET**

### FEATURES

- · For automatic insertion
- Compact, end stackable
- Fast switching
- Low drive current
- Easy paralleled
- Excellent temperature stability
- P-channel versatility
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

### DESCRIPTION

The HVMDIP technology is the key to Vishay's advanced line of power MOSFET transistors. The efficient geometry and unique processing of the HVMDIP design achieves very low on-state resistance combined with high transconductance and extreme device ruggedness.

The p-channel HVMDIPs are designed for application which require the convenience of reverse polarity operation. They retain all of the features of the more common n-channel HVMDIPs such as voltage control, very fast switching, ease of paralleling, and excellent temperature stability.

P-channels HVMDIPs are intended for use in power stages where complementary symmetry with n-channel devices offers circuit simplification. They are also very useful in drive stages because of the circuit versatility offered by the reverse polarity connection. Applications include motor control, audio amplifiers, switched mode converters, control circuits and pulse amplifiers.

ORDERING INFORMATION	
Package	HVMDIP
Lead (Pb)-free	IRFD9010PbF

<b>ABSOLUTE MAXIMUM RATINGS (T</b> C	= 25 °C, unle	ess otherwis	e noted)				
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-source voltage			V <sub>DS</sub>	- 50	V		
Gate-source voltage			V <sub>GS</sub>	± 20	- V		
Continuous drain current	V <sub>GS</sub> at -10 V	$T_{\rm C} = 25 \ ^{\circ}{\rm C}$ $T_{\rm C} = 100 \ ^{\circ}{\rm C}$	1	- 1.1			
		T <sub>C</sub> = 100 °C	I <sub>D</sub>	- 0.68	А		
Pulsed drain current <sup>a</sup>				- 8.8			
Linear derating factor				0.01	W/°C		
Inductive current, clamped	L = 100 µH see fig. 14		I <sub>LM</sub>	- 8.8			
Inductive current, unclamped (avalanche current)	see fig. 15		ΙL	- 1.5	— A		
Maximum power dissipation	T <sub>C</sub> = 25 °C		PD	1	W		
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 150	**			
Soldering recommendations (peak temperature)	For 10 s			300 <sup>d</sup>			

#### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b.  $V_{DD}$  = - 25 V, starting T<sub>J</sub> = 25 °C, L = 52 mH, R<sub>g</sub> = 25  $\Omega$ , I<sub>AS</sub> = - 2.0 A (see fig. 12)

c.  $I_{SD} \le -4.0$  A, dI/dt  $\le 75$  A/µs,  $V_{DD} \le V_{DS}$ ,  $T_J \le 175$  °C

d. 1.6 mm from case

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THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP. MAX.			UNIT			
Maximum Junction-to-Ambient	R <sub>thJA</sub>	- 120			°C/W			
<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 $^{\circ}$ C, u	inless otherw	ise noted)						
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static								
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> =	0 V, $I_D = -$	250 µA	- 50	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	I <sub>D</sub> = - 1 mA	-	- 0.091	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \ \mu A$			- 2.0	-	- 4.0	V
Gate-Source Leakage	I <sub>GSS</sub>		V <sub>GS</sub> = ± 20 V			-	± 500	nA
Zara Cata Valtaga Drain Current	Zero Gate Voltage Drain Current I <sub>DSS</sub>	V <sub>DS</sub> =	$V_{DS} = -50 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		-	-	- 250	
Zero Gale voltage Drain Current		V <sub>DS</sub> = - 40 V	$V_{DS}$ = - 40 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 °C			-	- 1000	μA
On-State Drain Current	I <sub>D(on)</sub>	$V_{GS} = 10 V$	$V_{DS} > I_{D(o)}$	<sub>n)</sub> x R <sub>DS(on)</sub> max.	- 1.1	-	-	Α
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V	I <sub>D</sub> =	- 0.58 A <sup>b</sup>	-	0.35	0.50	Ω
Forward Transconductance	9 <sub>fs</sub>	$V_{DS} = -20 \text{ V}, I_D = -2.4 \text{ A}$		1.7	2.5	-	S	
Dynamic								
Input Capacitance	C <sub>iss</sub>		$V_{GS} = 0 V$ ,		-	240	-	pF
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 V,$ f = 1.0 MHz, see fig. 5		V,	-	160	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			e fig. 5	-	30	-	
Total Gate Charge	Qg			-	7.2	11		
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = - 10 V	I <sub>D</sub> = - 4.7 see fi	′ A, V <sub>DS</sub> = 0.8 V g. 6 and 13 <sup>b</sup>	-	2.5	3.8	nC
Gate-Drain Charge	Q <sub>gd</sub>		000 11		-	2.7	4.1	
Turn-On Delay Time	t <sub>d(on)</sub>				-	6.1	9.2	
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 25 V, I <sub>D</sub> = - 4.7 A R <sub>g</sub> = 24 $\Omega$ , R <sub>D</sub> = 5.6 $\Omega$ , see fig. 10 <sup>b</sup>		-	47	71	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	13	20		
Fall Time	t <sub>f</sub>	eee ligt to			-	39		59
Internal Drain Inductance	L <sub>D</sub>	Between lead, 6 mm (0.25") from package and center of die contact			-	4.0	-	nH
Internal Source Inductance	L <sub>S</sub>				-	6.0	-	
Drain-Source Body Diode Characteristic	cs							
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the		-	-	- 1.1	А	
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>	p - n junction diode			-	-	- 8.8	
Body Diode Voltage	V <sub>SD</sub>	$T_J$ = 25 °C, $I_S$ = - 0.7 A, $V_{GS}$ = 0 $V^{\rm b}$			-	-	- 5.5	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			33	75	160	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = -4.7 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}^b$			0.090	0.22	0.52	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> and					y L <sub>S</sub> and	L <sub>D</sub> )

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. Pulse width  $\leq$  300 µs; duty cycle  $\leq$  2 %

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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

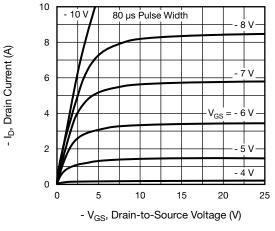


Fig. 1 - Typical Output Characteristics

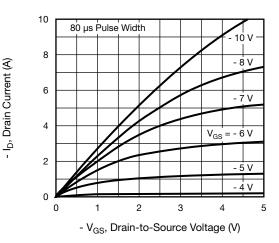


Fig. 2 - Typical Output Characteristics

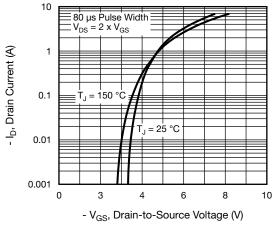


Fig. 3 - Typical Transfer Characteristics

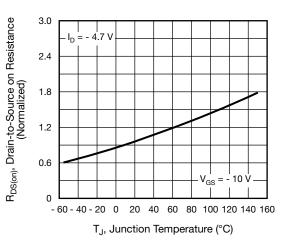


Fig. 4 - Normalized On-Resistance vs. Temperature

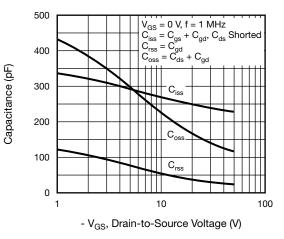


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

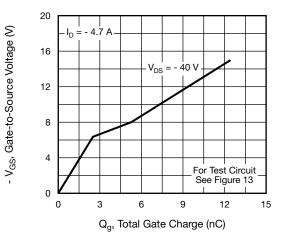


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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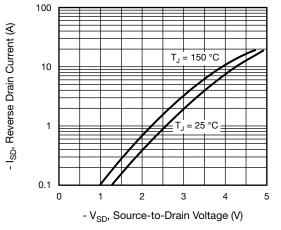


Fig. 7 - Typical Source-Drain Diode Forward Voltage

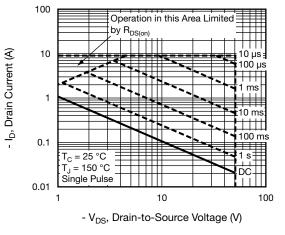


Fig. 8 - Maximum Safe Operating Area

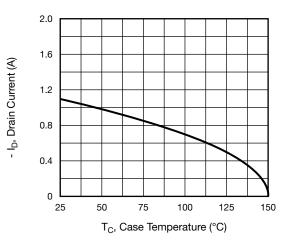


Fig. 9 - Maximum Drain Current vs. Case Temperature

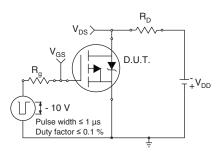


Fig. 10a - Switching Time Test Circuit

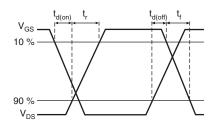
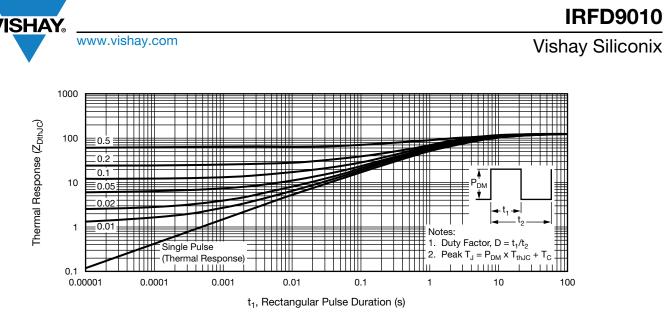


Fig. 10b - Switching Time Waveforms

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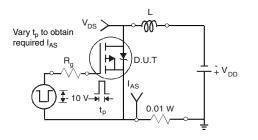


Fig. 12a - Unclamped Inductive Test Circuit

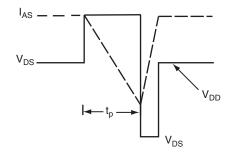


Fig. 12b - Unclamped Inductive Waveforms

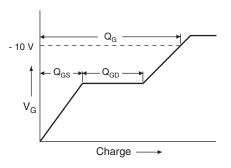


Fig. 13a - Basic Gate Charge Waveform

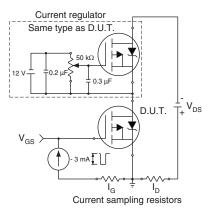


Fig. 13b - Gate Charge Test Circuit

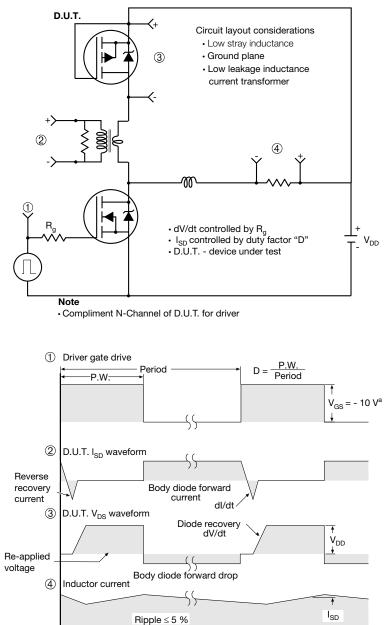
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#### Peak Diode Recovery dV/dt Test Circuit



a.  $V_{GS}$  = - 5 V for logic level and - 3 V drive devices

Note

Fig. 14 - For P-Channel

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